







CD74HC7266, CD54HC7266

SCHS219E - NOVEMBER 1998 - REVISED JUNE 2021

# CDx4HC7266 Quadruple 2-Input XNOR Gates

### 1 Features

- **Buffered** inputs
- Wide operating voltage range: 2 V to 6 V
- Wide operating temperature range: -55°C to +125°C
- Supports fanout up to 10 LSTTL loads
- Significant power reduction compared to LSTTL logic ICs

# 2 Applications

- Detect phase differences in input signals
- Create a selectable inverter / buffer

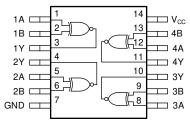
## 3 Description

This device contains four independent 2-input XNOR gates. Each gate performs the Boolean function  $Y = \overline{A \oplus B}$  in positive logic.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)				
CD74HC7266M	SOIC (14)	8.70 mm × 3.90 mm				
CD74HC7266E	PDIP (14)	19.30 mm × 6.40 mm				
CD54HC7266F	CDIP (14)	21.30 mm × 7.60 mm				

For all available packages, see the orderable addendum at the end of the data sheet.



**Functional pinout** 



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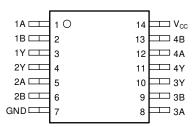
## **4 Revision History**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

#### 



# **5 Pin Configuration and Functions**



D, N, or J Package 14-Pin SOIC, PDIP, or CDIP Top View

## **Pin Functions**

	PIN	I/O	DESCRIPTION
NAME	NO.	<b>-</b> 1/O	DESCRIPTION
1A	1	Input	Channel 1, Input A
1B	2	Input	Channel 1, Input B
1Y	3	Output	Channel 1, Output Y
2Y	4	Output	Channel 2, Output Y
2A	5	Input	Channel 2, Input A
2B	6	Input	Channel 2, Input B
GND	7	_	Ground
3A	8	Input	Channel 3, Input A
3B	9	Input	Channel 3, Input B
3Y	10	Output	Channel 3, Output Y
4Y	11	Output	Channel 4, Output Y
4A	12	Input	Channel 4, Input A
4B	13	Input	Channel 4, Input B
V <sub>CC</sub>	14	_	Positive Supply



## **6 Specifications**

# **6.1 Absolute Maximum Ratings**

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		-0.5	7	V
I <sub>IK</sub>	Input clamp current <sup>(2)</sup>	$V_1 < -0.5 \text{ V or } V_1 > V_{CC} + 0.5 \text{ V}$		±20	mA
I <sub>OK</sub>	Output clamp current <sup>(2)</sup>	$V_O$ < $-0.5$ V or $V_O$ > $V_{CC}$ + $0.5$ V		±20	mA
Io	Continuous output current	t current $V_O > -0.5 \text{ V or } V_O < V_{CC} + 0.5 \text{ V}$		±25	mA
	Continuous current through V <sub>CC</sub> or GND	·		±50	mA
TJ	Junction temperature <sup>(3)</sup>			150	°C
	Lead temperature (soldering 10s)	SOIC - lead tips only		300	°C
T <sub>stg</sub>	Storage temperature	-65	150	°C	

- (1) Stresses beyond those listed under Absolute Maximum Rating may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Condition. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) Guaranteed by design.

## **6.2 Recommended Operating Conditions**

over operating free-air temperature range (unless otherwise noted)

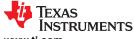
		,	MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2	5	6	V
		V <sub>CC</sub> = 2 V	1.5	-		
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			V
		V <sub>CC</sub> = 6 V	4.2			
		V <sub>CC</sub> = 2 V			0.5	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35	V
		V <sub>CC</sub> = 6 V			1.8	
VI	Input voltage		0		V <sub>CC</sub>	V
Vo	Output voltage		0		V <sub>CC</sub>	V
		V <sub>CC</sub> = 2 V			1000	
t <sub>t</sub>	Input transition time	V <sub>CC</sub> = 4.5 V			500	ns
		V <sub>CC</sub> = 6 V			400	
T <sub>A</sub>	Operating free-air temperature		-55		125	°C

## 6.3 Thermal Information

		CD74				
	THERMAL METRIC <sup>(1)</sup>	THERMAL METRIC <sup>(1)</sup> N (PDIP)				
		14 PINS	14 PINS			
$R_{\theta JA}$	Junction-to-ambient thermal resistance	64.8	133.6	°C/W		
R <sub>0JC(top)</sub>	Junction-to-case (top) thermal resistance	52.6	89.0	°C/W		
R <sub>θJB</sub>	Junction-to-board thermal resistance	44.6	89.5	°C/W		
$\Psi_{JT}$	Junction-to-top characterization parameter	32.2	45.5	°C/W		
$\Psi_{JB}$	Junction-to-board characterization parameter	44.3	89.1	°C/W		

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		CD74H		
	THERMAL METRIC <sup>(1)</sup>	N (PDIP)	UNIT	
		14 PINS	14 PINS	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

## **6.4 Electrical Characteristics**

over operating free-air temperature range; typical values measured at  $T_A$  = 25°C (unless otherwise noted).

						Opera	ting free	air tem	peratur	e (T <sub>A</sub> )				
F	PARAMETER	TEST CO	TEST CONDITIONS		25°C			–40°	C to 85	°C	–55°0	C to 125	°C	UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
				2 V	1.9			1.9			1.9			
	High-level output voltage	$V_{I} = V_{IH}$ or $V_{IL}$	I <sub>OH</sub> = –20 μΑ	4.5 V	4.4			4.4			4.4			
				6 V	5.9			5.9			5.9	,		V
V <sub>OH</sub>			I <sub>OH</sub> = -4 mA	4.5 V	3.98			3.84			3.7			
					I <sub>OH</sub> = -5.2 mA	6 V	5.48			5.34			5.2	
				2 V			0.1			0.1			0.1	
			I <sub>OL</sub> = 20 μΑ	4.5 V			0.1			0.1			0.1	
V <sub>OL</sub>	Low-level output			6 V			0.1			0.1			0.1	V
OL	voltage	V <sub>IL</sub>	I <sub>OL</sub> = 4 mA	4.5 V			0.26			0.33			0.4	-
			I <sub>OL</sub> = 5.2 mA	6 V			0.26			0.33			0.4	
I <sub>1</sub>	Input leakage current	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V			±0.1			±1			±1	μΑ
I <sub>CC</sub>	Supply current	V <sub>I</sub> = V <sub>CC</sub> or 0	I <sub>O</sub> = 0	6 V			2			20			40	μΑ
C <sub>i</sub>	Input capacitance						10			10			10	pF

# **6.5 Switching Characteristics**

over operating free-air temperature range; typical values measured at TA = 25°C (unless otherwise noted).

				TEST		Operating free-air temperature (T <sub>A</sub> )												
	PARAMETER		PARAMETER	FROM		CONDITIO		Vcc		25°C		-40°	C to 8	5°C	-55°C	C to 12	25°C	UNIT
				NS		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX				
					2 V			115			145			150				
	Duran a satisfaction delection	A or B Y	Υ	"	4.5 V			23			29			35				
t <sub>pd</sub>	Propagation delay				6 V			30			25			30	ns			
		A or B	Υ	C <sub>L</sub> = 15 pF	5 V		9											
		nsition-time		C <sub>L</sub> = 50 pF	2 V			75			95			110				
t <sub>t</sub>	Transition-time		Υ		4.5 V			15			19			22	ns			
					6 V			13			16			19				



## **6.6 Operating Characteristics**

over operating free-air temperature range; typical values measured at T<sub>A</sub> = 25°C (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP MAX	UNIT
Cpc	Power dissipation capacitance per gate	No load	2 V to 6 V		33	pF

# **6.7 Typical Characteristics**

T<sub>A</sub> = 25°C

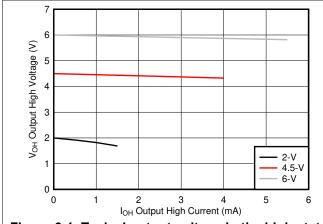


Figure 6-1. Typical output voltage in the high state  $(V_{OH})$ 

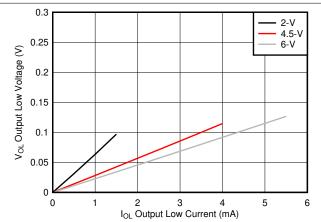
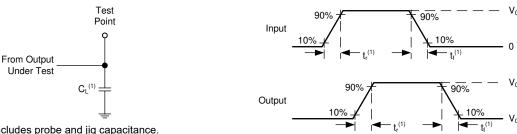


Figure 6-2. Typical output voltage in the low state  $(V_{OL})$ 



## 7 Parameter Measurement Information

- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_t < 6$  ns.
- The outputs are measured one at a time, with one input transition per measurement.

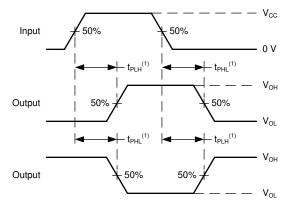


A.  $C_L$ = 50 pF and includes probe and jig capacitance.

Figure 7-1. Load Circuit

A.  $t_t$  is the greater of  $t_r$  and  $t_f$ .

Figure 7-2. Voltage Waveforms Transition Times



A. The maximum between t<sub>PLH</sub> and t<sub>PHL</sub> is used for t<sub>pd</sub>.

Figure 7-3. Voltage Waveforms Propagation Delays

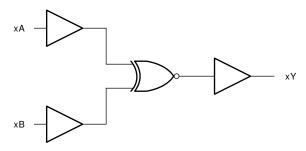


## **8 Detailed Description**

### 8.1 Overview

This device contains four independent 2-input XNOR gates. Each gate performs the Boolean function  $Y = \overline{A \oplus B}$  in positive logic.

## 8.2 Functional Block Diagram



### 8.3 Feature Description

## 8.3.1 Balanced CMOS Push-Pull Outputs

A balanced output allows the device to sink and source similar currents. The drive capability of this device may create fast edges into light loads so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the output power of the device to be limited to avoid damage due to over-current. The electrical and thermal limits defined in the *Section 6.1* must be followed at all times.

The CD74HC7266 can drive a load with a total capacitance less than or equal to the maximum load listed in the Section 6.5 connected to a high-impedance CMOS input while still meeting all of the datasheet specifications. Larger capacitive loads can be applied, however it is not recommended to exceed the provided load value. If larger capacitive loads are required, it is recommended to add a series resistor between the output and the capacitor to limit output current to the values given in the Section 6.1.

#### 8.3.2 Standard CMOS Inputs

Standard CMOS inputs are high impedance and are typically modeled as a resistor from the input to ground in parallel with the input capacitance given in the Section 6.4. The worst case resistance is calculated with the maximum input voltage, given in the Section 6.1, and the maximum input leakage current, given in the Section 6.4, using ohm's law ( $R = V \div I$ ).

Signals applied to the inputs need to have fast edge rates, as defined by the input transition time in the *Section 6.2* to avoid excessive current consumption and oscillations. If a slow or noisy input signal is required, a device with a Schmitt-trigger input should be used to condition the input signal prior to the standard CMOS input.



## 8.3.3 Clamp Diode Structure

The inputs and outputs to this device have both positive and negative clamping diodes as depicted in Figure 8-1.

### **CAUTION**

Voltages beyond the values specified in the Section 6.1 table can cause damage to the device. The recommended input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

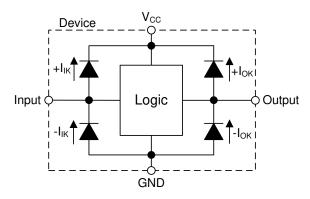


Figure 8-1. Electrical Placement of Clamping Diodes for Each Input and Output

## **8.4 Device Functional Modes**

**Table 8-1. Function Table** 

INP	INPUTS						
Α	В	Y					
L	L	Н					
L	Н	L					
Н	L	L					
Н	Н	Н					

## 9 Application and Implementation

#### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

## 9.1 Application Information

In this application, a 2-input XNOR gate is used as a phase difference detector as shown in *Figure 9-1*. The remaining three gates can be used for other applications in the system, or the inputs can be grounded and the channels left unused.

The device is used to identify phase difference between a reference clock and another input clock. Whenever the clock states are different, the XNOR output will pulse HIGH until the clocks return to the same state. The output is fed into a low-pass filter to obtain a DC representation of the phase difference.

## 9.2 Typical Application

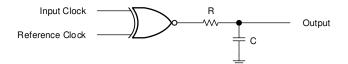


Figure 9-1. Typical application schematic

## 9.2.1 Design Requirements

#### 9.2.1.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the Section 6.2. The supply voltage sets the device's electrical characteristics as described in the Section 6.4.

The supply must be capable of sourcing current equal to the total current to be sourced by all outputs of the CD74HC7266 plus the maximum supply current,  $I_{CC}$ , listed in the Section 6.4. The logic device can only source or sink as much current as it is provided at the supply and ground pins, respectively. Be sure not to exceed the maximum total current through GND or  $V_{CC}$  listed in the Section 6.1.

Total power consumption can be calculated using the information provided in CMOS Power Consumption and  $C_{pd}$  Calculation.

Thermal increase can be calculated using the information provided in Thermal Characteristics of Standard Linear and Logic (SLL) Packages and Devices.

#### **CAUTION**

The maximum junction temperature,  $T_J(max)$  listed in the Section 6.1, is an additional limitation to prevent damage to the device. Do not violate any values listed in the Section 6.1. These limits are provided to prevent damage to the device.

#### 9.2.1.2 Input Considerations

Unused inputs must be terminated to either  $V_{CC}$  or ground. These can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input is to be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The resistor size is limited by drive current of the controller, leakage current into the CD74HC7266, as specified in the Section 6.4, and the desired input transition rate. A 10-k $\Omega$  resistor value is often used due to these factors.

The CD74HC7266 has standard CMOS inputs, so input signal edge rates cannot be slow. Slow input edge rates can cause oscillations and damaging shoot-through current. The recommended rates are defined in the Section

Refer to the Section 8.3 for additional information regarding the inputs for this device.

#### 9.2.1.3 Output Considerations

The positive supply voltage is used to produce the output HIGH voltage. Drawing current from the output will decrease the output voltage as specified by the VOH specification in the Section 6.4. Similarly, the ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V<sub>OL</sub> specification in the Section 6.4.

Unused outputs can be left floating. Do not connect outputs directly to V<sub>CC</sub> or ground.

Refer to Section 8.3 for additional information regarding the outputs for this device.

#### 9.2.2 Detailed Design Procedure

- 1. Add a decoupling capacitor from V<sub>CC</sub> to GND. The capacitor needs to be placed physically close to the device and electrically close to both the  $V_{CC}$  and GND pins. An example layout is shown in the Section 11.
- Ensure the capacitive load at the output is ≤ 70 pF. This is not a hard limit, however it will ensure optimal performance. This can be accomplished by providing short, appropriately sized traces from the CD74HC7266 to the receiving device.
- 3. Ensure the resistive load at the output is larger than  $(V_{CC} / I_O(max)) \Omega$ . This will ensure that the maximum output current from the Section 6.1 is not violated. Most CMOS inputs have a resistive load measured in megaohms; much larger than the minimum calculated above.
- 4. Thermal issues are rarely a concern for logic gates, however the power consumption and thermal increase can be calculated using the steps provided in the application report, CMOS Power Consumption and Cpd Calculation

### 9.2.3 Application Curves

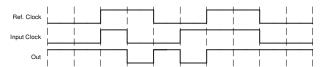


Figure 9-2. Typical application timing diagram



# 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the Section 6.2. Each  $V_{CC}$  terminal should have a bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in Figure 11-1.



## 11 Layout

## 11.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

### 11.2 Layout Example

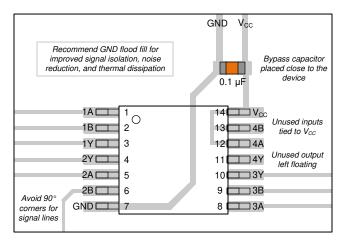


Figure 11-1. Example layout for the CD74HC7266



## 12 Device and Documentation Support

## **12.1 Documentation Support**

#### 12.1.1 Related Documentation

For related documentation see the following:

- HCMOS Design Considerations
- CMOS Power Consumption and CPD Calculation
- · Designing with Logic

## 12.2 Support Resources

TI E2E<sup>™</sup> support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

#### 12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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## 12.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 12.5 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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9-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
8404302CA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8404302CA CD54HC7266F3A
CD54HC7266F3A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8404302CA CD54HC7266F3A
CD54HC7266F3A.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8404302CA CD54HC7266F3A
CD74HC7266E	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC7266E
CD74HC7266E.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC7266E
CD74HC7266M	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-55 to 125	HC7266M
CD74HC7266M96	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 125	HC7266M
CD74HC7266M96.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC7266M
CD74HC7266MT	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-55 to 125	HC7266M

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE OPTION ADDENDUM**

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF CD54HC7266, CD74HC7266:

Catalog: CD74HC7266

Military: CD54HC7266

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC7266M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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## \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	CD74HC7266M96	SOIC	D	14	2500	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

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## **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HC7266E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC7266E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC7266E.A	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC7266E.A	N	PDIP	14	25	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



#### NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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